Unit: mm

TOSHIBA Field-Effect Transistor Silicon N / P Channel MOS Type

SSM6L35FE

High-Speed Switching Applications

Analog Switch Applications

N-ch: 1.2-V drive
 P-ch: 1.2-V drive
 N-ch, P-ch, 2-in-1

• Low ON-resistance Q1 N-ch: R_{on} = 20 Ω (max) (@V_{GS} = 1.2 V)

: R_{on} = 8 Ω (max) (@V_{GS} = 1.5 V)

: $R_{ON} = 4 \Omega \text{ (max) } (@V_{GS} = 2.5 \text{ V})$

: $R_{on} = 3 \Omega \text{ (max) } (@V_{GS} = 4.0 \text{ V})$

Q2 P-ch: R_{on} = 44 Ω (max) (@V_{GS} = -1.2 V)

: R_{OI} = 22 Ω (max) (@V_{GS} = -1.5 V) : R_{OI} = 11 Ω (max) (@V_{GS} = -2.5 V)

: $R_{on} = 8 \Omega \text{ (max) (@V}_{GS} = -4.0 \text{ V)}$

Q1 Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	20	٧	
Gate-source voltage	V_{GSS}	±10	V	
Drain current	DC	I _D	180	mA
Drain current	Pulse	I_{DP}	360	MA

Q2 Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit				
Drain-source voltage	V_{DSS}	-20	V				
Gate-source voltage	V_{GSS}	±10	V				
Drain current	DC	I _D	-100	mA			
Dialii cuirent	Pulse	I _{DP}	-200	IIIA			

Absolute Maximum Ratings (Ta = 25 °C) (Common to the Q1, Q2)

Characteristic	Symbol	Rating	Unit
Drain power dissipation	P _D (Note 1)	150	mW
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating

Mounted on an FR4 board (25.4 mm \times 25.4 mm \times 1.6 mm, Cu Pad: 0.135 mm² \times 6)

Start of commercial production 2008-03

1.6±0.05	1.0±0.05 ₁	\$.0. \$ \\$.0	1 2 3	1.2±0.0)5	6 5	-
	0,55±0.05						را آ 0.12±0.05
ES	86		2	1.Source1 2.Gate1 3.Drain2	5.	Sour Gate Drair	2

2-2N1D

1.6±0.05

Weight: 3.0 mg (typ.)

JEDEC JEITA TOSHIBA

Q1 Electrical Characteristics (Ta = 25°C)

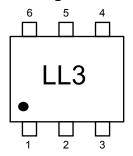
Characteristics		Symbol	Test Condition		Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±10	μΑ
Drain-source brea	ıkdown voltage	V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0V$		20	_	_	V
Drain cutoff currer	nt	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0V		_	_	1	μΑ
Gate threshold voltage		V _{th}	$V_{DS} = 3 \text{ V}, I_{D} = 1 \text{ mA}$		0.4	_	1.0	V
Forward transfer admittance		Y _{fs}	$V_{DS} = 3 \text{ V}, I_{D} = 50 \text{ mA}$	(Note 2)	115	_	_	mS
			$I_D = 50 \text{ mA}, V_{GS} = 4 \text{ V}$	(Note 2)	_	1.5	3	Ω
Drain aguras ON	Drain-source ON-resistance		$I_D = 50 \text{ mA}, V_{GS} = 2.5 \text{ V}$	(Note 2)	_	2	4	
Drain-source ON-			$I_D = 5 \text{ mA}, V_{GS} = 1.5 \text{ V}$	(Note 2)	_	3	8	
			I _D = 5 mA, V _{GS} = 1.2 V	(Note 2)	_	5	20	
Input capacitance		C _{iss}	V _{DS} = 3 V, V _{GS} = 0V, f = 1 MHz		_	9.5	_	pF
Reverse transfer of	Reverse transfer capacitance				_	4.1	_	
Output capacitance		Coss			_	9.5	_	
0 11 11 11	Turn-on time	t _{on}	V _{DD} = 3 V, I _D = 50 mA, V _{GS} = 0 to 2.5 V		_	115	_	
Switching time	Turn-off time	t _{off}			_	300	_	ns
Drain-source forward voltage		V _{DSF}	$I_D = -180 \text{ mA}, V_{GS} = 0V$	(Note 2)	_	-0.9	-1.2	V

Q2 Electrical Characteristics (Ta = 25°C)

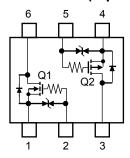
Charac	Characteristics Symbol Test Condition		Min	Тур.	Max	Unit		
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$		_	_	±10	μΑ
Drain-source brea	kdown voltage	V (BR) DSS	$I_D = -0.1 \text{ mA}, V_{GS} = 0 \text{ V}$		-20	_	_	V
Drain cutoff curren	t	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V		_	_	-1	μΑ
Gate threshold voltage		V _{th}	$V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$		-0.4	_	-1.0	V
Forward transfer admittance		Y _{fs}	$V_{DS} = -3 \text{ V}, I_{D} = -50 \text{ mA}$	(Note 2)	77	_	_	mS
Drain-source ON-resistance		R _{DS} (ON)	$I_D = -50 \text{ mA}, V_{GS} = -4 \text{ V}$	(Note 2)	_	4.3	8	Ω
			$I_D = -50 \text{ mA}, V_{GS} = -2.5 \text{ V}$	(Note 2)	_	5.6	11	
			I _D = -5 mA, V _{GS} = -1.5 V	(Note 2)	_	8.2	22	
			I _D = -2 mA, V _{GS} = -1.2 V	(Note 2)	_	11	44	
Input capacitance		C _{iss}	V _{DS} = -3 V, V _{GS} = 0 V, f = 1 MHz		_	12.2	_	pF
Reverse transfer capacitance		C _{rss}			_	6.5	_	
Output capacitance		C _{oss}		_	10.4	_		
Switching time	Turn-on time	t _{on}	$V_{DD} = -3 \text{ V}, I_D = -50 \text{ mA},$		_	175	_	
	Turn-off time	t _{off}	V _{GS} = 0 to -2.5 V		_	251	_	ns
Drain-source forward voltage		V _{DSF}	I _D = 100 mA, V _{GS} = 0 V	(Note 2)	_	0.83	1.2	V

Note 2: Pulse test

Marking

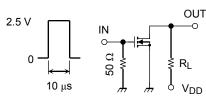


Equivalent Circuit (top view)



Q1 Switching Time Test Circuit

(a) Test Circuit



 $V_{DD} = 3 V$ Duty ≤ 1%

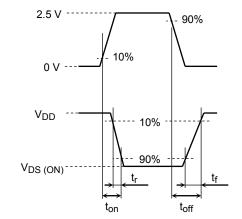
 $V_{IN}\text{:}\ t_{r},\ t_{f}<5\ ns$

 $(Z_{out} = 50 \Omega)$ Common Source

 $Ta = 25^{\circ}C$

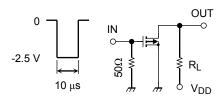


(c) V_{OUT}



Q2 Switching Time Test Circuit

(a) Test Circuit



 $V_{DD} = -3 V$

Duty ≤ 1%

 V_{IN} : t_r , $t_f < 5$ ns

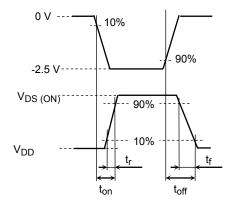
 $(Z_{out} = 50 \Omega)$

Common Source

 $Ta = 25^{\circ}C$

(b) V_{IN}





Q1 Usage Considerations

Let Vth be the voltage applied between gate and source that causes the drain current (ID) to below (1 mA for the Q1 of the SSM6L35FE). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

Take this into consideration when using the device.

Q2 Usage Considerations

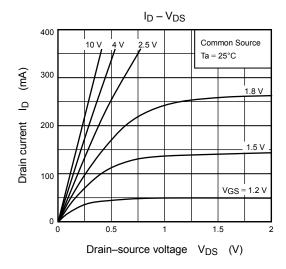
Let Vth be the voltage applied between gate and source that causes the drain current (ID) to below (-1 mA for the Q2 of the SSM6L35FE). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th.} This relationship can be expressed as: V_{GS(off)} < V_{th} < V_{GS(on)}.

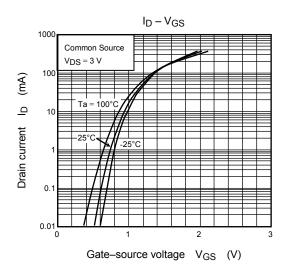
Take this into consideration when using the device.

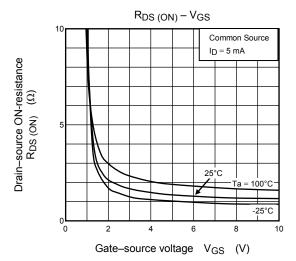
Handling Precaution

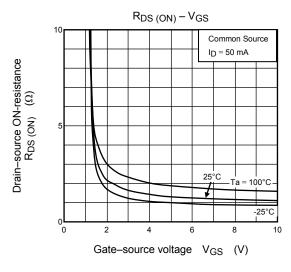
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

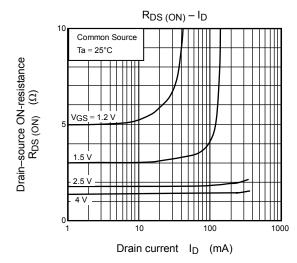
Q1 (N-ch MOSFET)

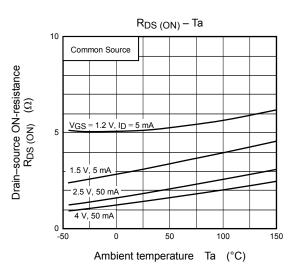




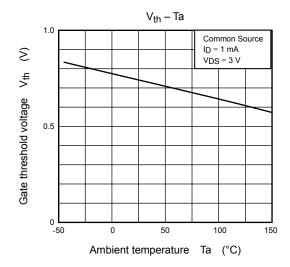


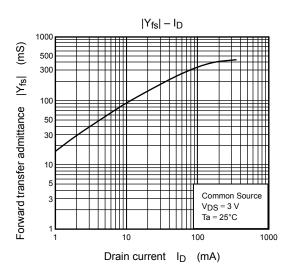


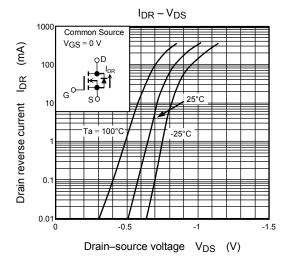


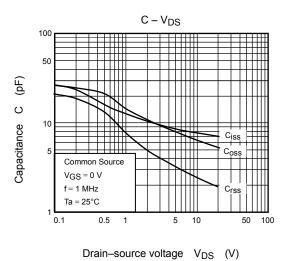


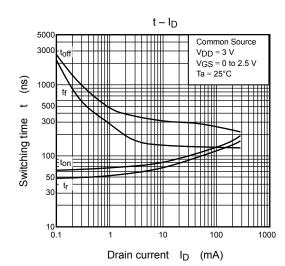
Q1 (N-ch MOSFET)





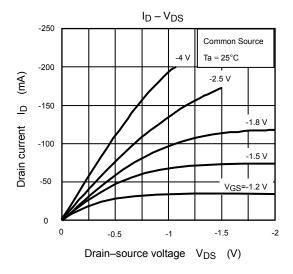


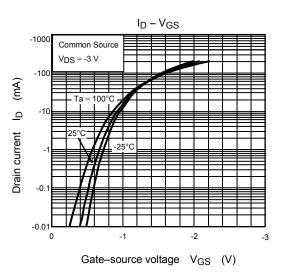


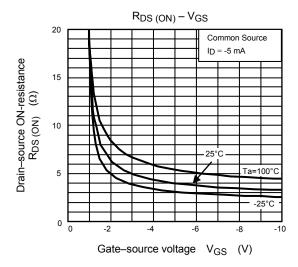


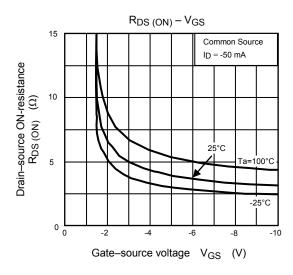
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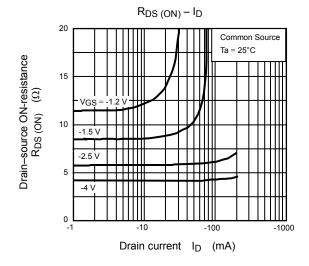
Q2 (P-ch MOSFET)

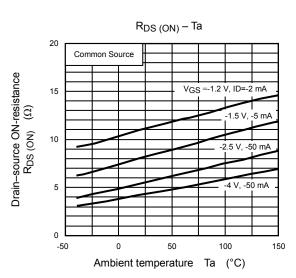




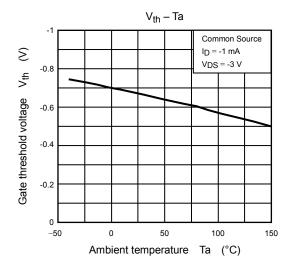


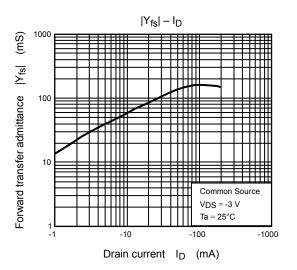


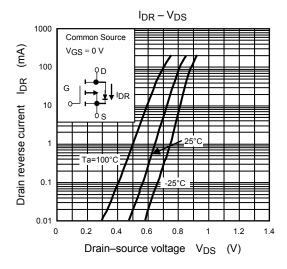


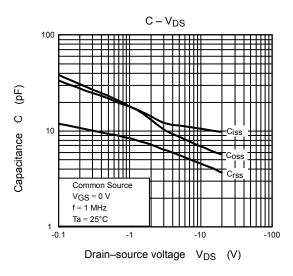


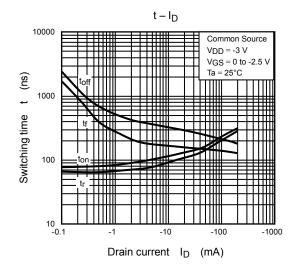
Q2 (P-ch MOSFET)

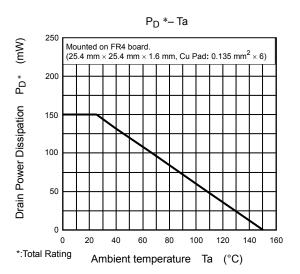












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